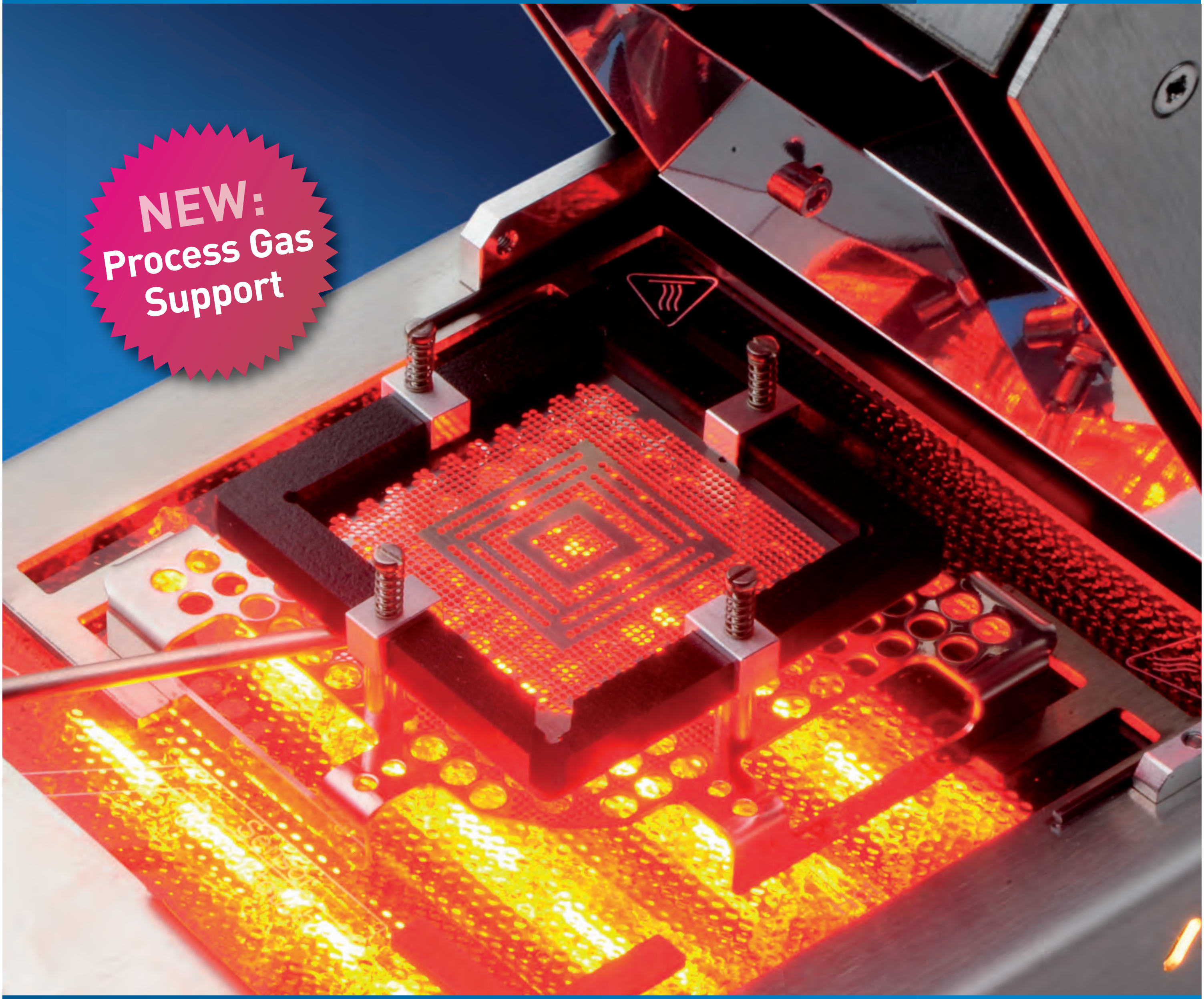


EXPERT MiniOven-04
For Reballing and Prebumping
of SMD Components

www.martin-smt.de

MARTIN®
a finetech company

Precision and Quality Always a Standard

The new EXPERT MiniOven-04, with Reball and Prebump Kits, provides convenient, successful results. New air convection technology, process gas supply, and intuitive feature control provide clear advantages: perfect wetting behavior of lead free solder, component safety, and long term liability.

Powerful 400W IR-Bottom-Heater

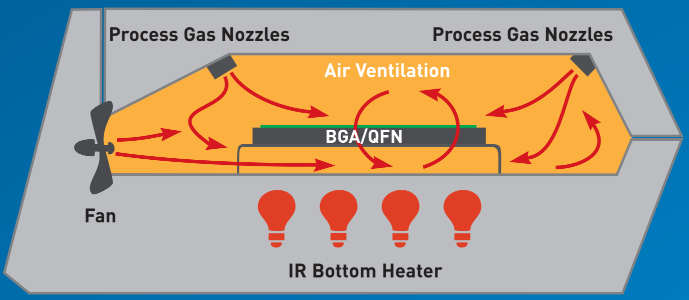
Improved temperature distribution through convection

LCD display with intuitive profile control

Process gas supply minimizes unwanted oxidation NEW

Uniform Heating

An optimized component heating process in the MiniOven-04 is the result of the combination of IR-radiation and new convection technology. For demanding applications, process gas can be utilized.



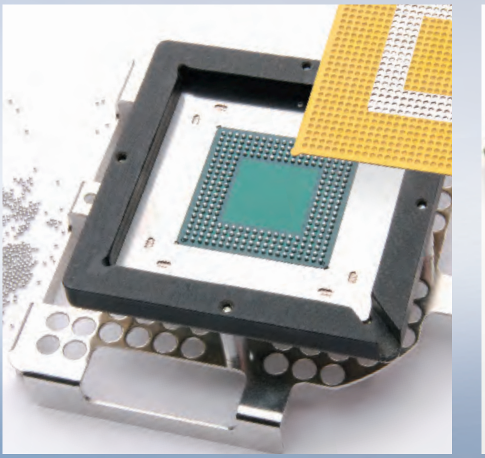
Air Ventilation inside the MiniOven-04

Reballing and Prebumping for All Applications

The new MiniOven-04 is perfectly suitable for a wide range of applications, from small QFNs to very large BGAs. This is due to our extensive selection of stencils and masks for almost any standard chip. For new components, we will design and manufacture stencils on request – a service which MARTIN has successfully provided for many years.

Reballing


Filling solder spheres in the stencil holes.

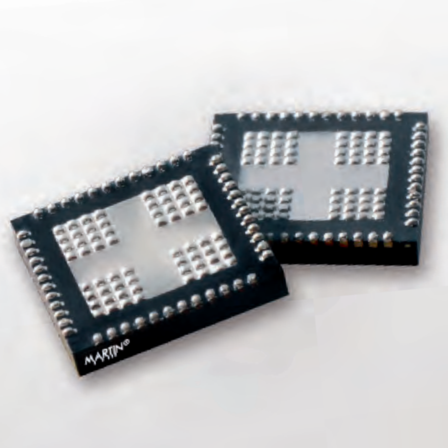

BGA in frame after reflow process


New reballed BGA

Prebumping


Installation of stencil into prebumping tool.


Squeegee of solder paste to stencil

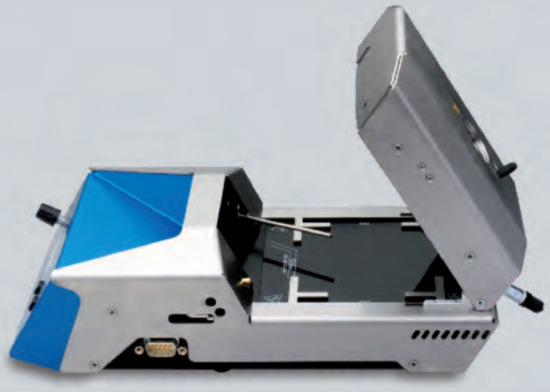


New prebumped QFN

Improved Control

Up to 99 MiniOven profiles can be used and edited via a two-button interface. The integrated database makes it easy to find the optimal parameters. New features such as adjustable hold time, temperature offset, and temperature damping improve process stability.

EXPERT MiniOven-04



Technical Data

MiniOven-04 S

Dim. over all:	140 x 290 x 83 mm
Dim. Heating Chamber:	80 x 80 x 20 mm
Wattage (max.):	400 W
Process Temp-Range:	100°C - 260°C
Process Gas Inlet:	not supported
Temp-Measurement:	K-type Sensor
Programs:	99

Technical Data

MiniOven-04 N

Dim. over all:	140 x 290 x 83 mm
Dim. Heating Chamber:	80 x 80 x 20 mm
Wattage (max.):	400 W
Process Temp-Range:	100°C - 260°C
Process Gas Inlet:	4 nozzles
Temp-Measurement:	K-type Sensor
Programs:	99

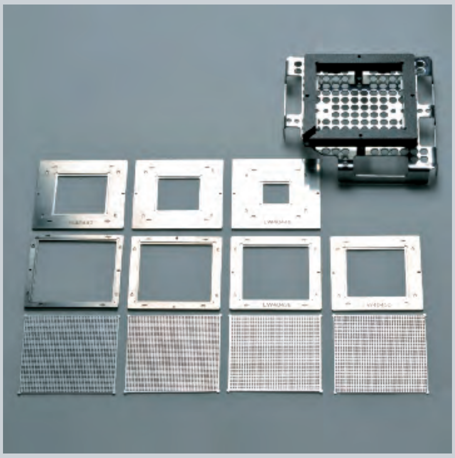
Delivery Package MiniOven-04S / -04N

- MiniOven-04S / -04N Basis Unit
- SMD Hook, Brush, Lens
- Kapton Tape, Cutter
- Manual and Rework ABC

Optional:

- Reball-04 Set Standard
- Reball-04 Set PS3
- Prebump-04 Set QFN

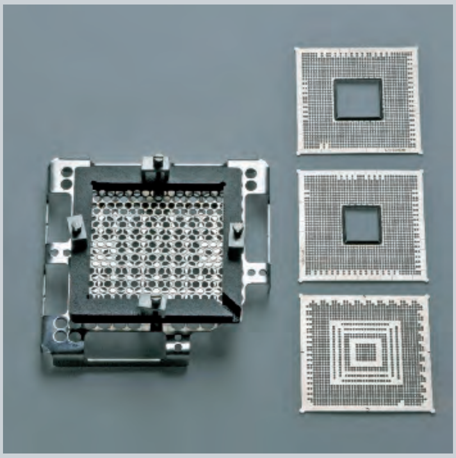
Reball-04 Set Standard



Includes:

- Reballing-Holder 45 x 45 mm²
- Reballing Frame Set for BGAs (7 pcs)
- 4 Reballing Masks for BGAs with Pitch 1.00 mm and 1.27 mm

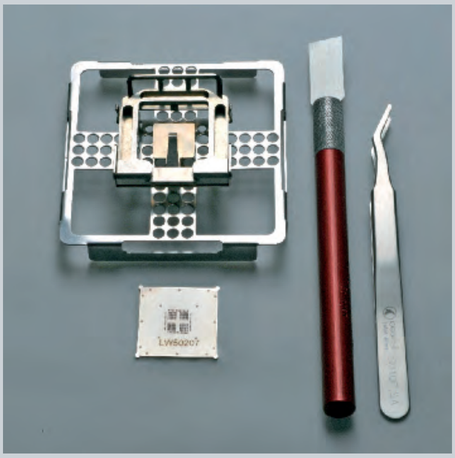
Reball-04 Set PS3



Includes:

- Reballing-Holder 45 x 45 mm² with Spring Loaded Clamps
- 3 Masks for PS3 BGA reballing, Pitch 1.00 mm

Prebump-04 Set QFN



Includes:

- Prebump Tool
- Squeegee Tool, Tweezers
- 1 Standard Stencil

Konzept und Realisierung: Sternwerfer Design

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02/2011